

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with strikethrough. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims 10-27 without prejudice:

1. (ORIGINAL) An electronic device having mounted thereon a microelectromechanical system element comprising a micromachine component and electronic component for operation of said micromachine component formed on a substrate, in which an operating space for said micromachine component is defined by said substrate and a lid bonded covering an active surface of said substrate, and said electronic component and wiring patterns of said lid are electrically connected at a bonded part of said substrate and said lid.
2. (ORIGINAL) An electronic device as set forth in claim 1, in which said bonded part is an ultrasonic bonded part of said substrate and said lid.
3. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and/or said lid further have a cavity at said operating space side.
4. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and a lid having no wiring pattern further comprise, between them, an intermediate member provided with an opening for operation of said micromachine component and wiring patterns and said electronic component and the wiring patterns of said intermediate member are electrically connected.
5. (ORIGINAL) An electronic device as set forth in claim 2, in which said substrate, said lid, and an intermediate member arranged in accordance with need between said substrate and said lid further comprise a second continuous ultrasonic bonded part formed in contact with an outer periphery of said operating space side of said substrate and other members without interruption.

6. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and/or said lid further comprise conductor-filled vias formed passing through them in a thickness direction.

7. (ORIGINAL) An electronic device as set forth in claim 4, in which said intermediate member further comprises conductor-filled vias formed passing through it in a thickness direction.

8. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, which further comprises a bonded sealing resin surrounding an outside surface of said bonded part.

9. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which a plurality of said electronic devices are those produced batch-wise at the same time by a wafer level package process.

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